

Claims

1. Components, characterized by
 - a glass substrate (11)
 - 5 • an organic light-emitting diode (12) arranged on said glass substrate (11), and
 - a glass cover (13) which is arranged over the organic light-emitting diode (12) and is glued at the edge (14) to the glass substrate (11),
10 said cover being produced from a glass plate by three-dimensional removal of material using a blasting method.
- 15 2. Components of claim 1, characterized in that the edge of the glass cover has been superficially roughened.
- 20 3. Components of claim 1 or 2, characterized in that the glass cover is bonded to the glass substrate using an organic adhesive.
- 25 4. Components of claim 3, characterized in that the adhesive is UV-curable.
- 25 5. Components of claim 3 or 4, characterized in that the adhesive is an epoxy resin.
- 30 6. A process for producing components of one or more of claims 1 to 5, characterized in that a large number of recesses is produced in a glass plate by three-dimensional removal of material using a blasting method, in that using this glass plate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate is
35 encapsulated, and in that subse-

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quently the resulting components are at least partly individualized.